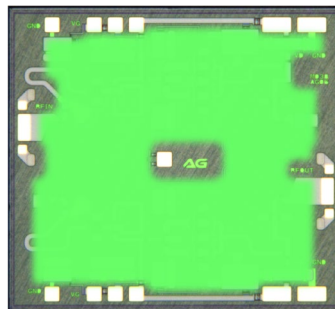
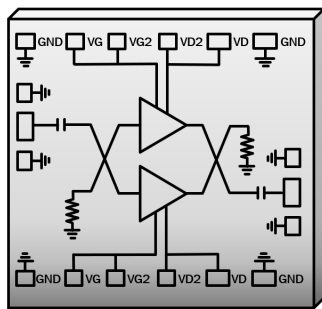


Typical Applications

- Point-to-Point Radio
- K-Band SATCOM

Features

- Frequency Range: 17.3 – 20.2 GHz
- Gain: 21 dB
- PAE: 30% @ 35 dBm Pout
- Psat: + 35dBm
- Bias: VD = +28V, IDQ = 100mA, VG = -1.56
- 50Ω Matched Input/Output DC blocked
- Chip Size: 2.4 x 2.2 x 0.1 mm

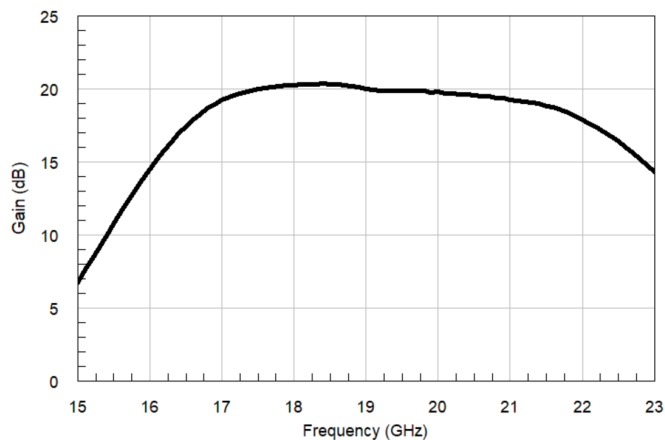


Electrical Specifications (TA = +25°C, VD = +28V, IDQ = 100mA, VG = -1.72)

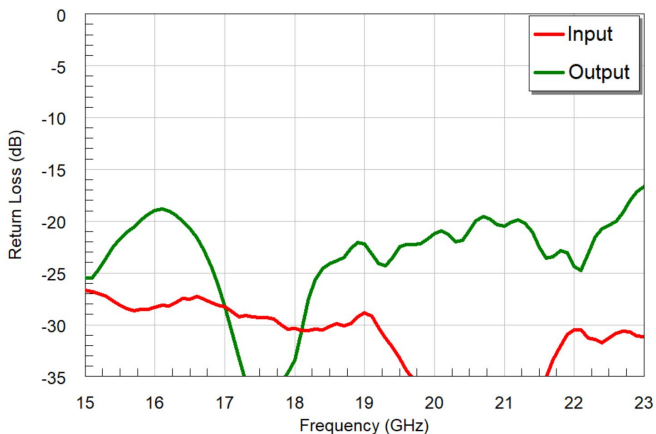
| Parameter | Units | Minimum | Typical | Maximum |
|----------------------|-------|---------|---------|---------|
| Frequency | GHz | 17.3 | | 20.2 |
| Gain | dB | | 20 | |
| Gain Flatness | dB | | ± 1 | |
| Input Return Loss | dB | | 26 | |
| Output Return Loss | dB | | 21 | |
| PAE | % | | 26 | |
| Psat | dBm | | 35 | |
| Supply Voltage (Vdq) | V | | +28 | |
| Supply Current (Idq) | mA | | 100 | |
| DC Dissipated Power | W | | 2.8 | |
| Package Type | | | Die | |

Performance Graphs

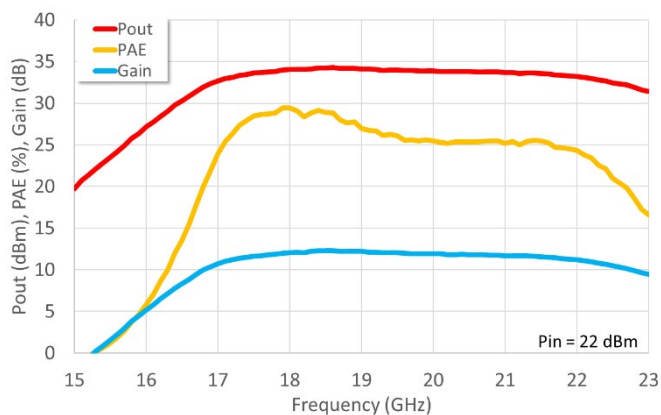
Gain



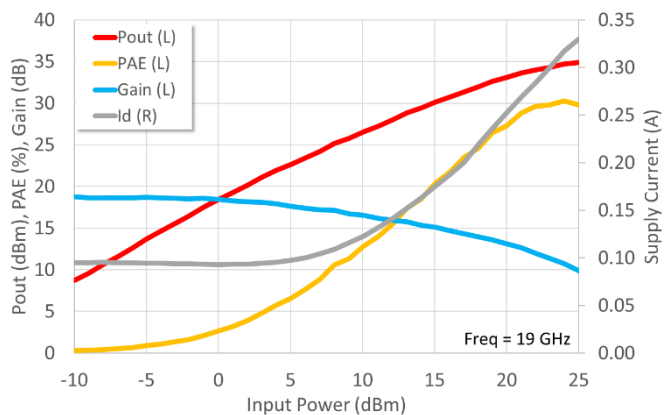
Return Losses



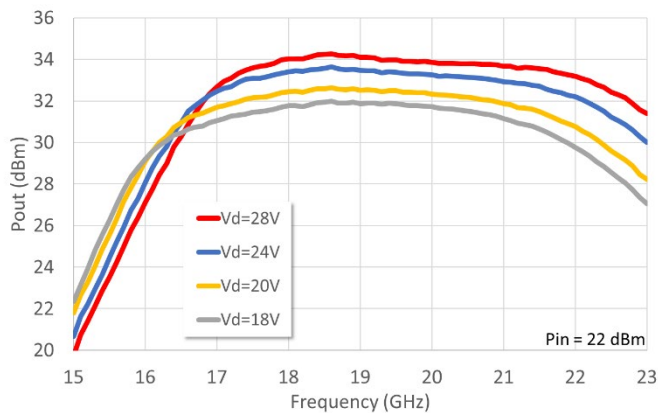
Frequency Response



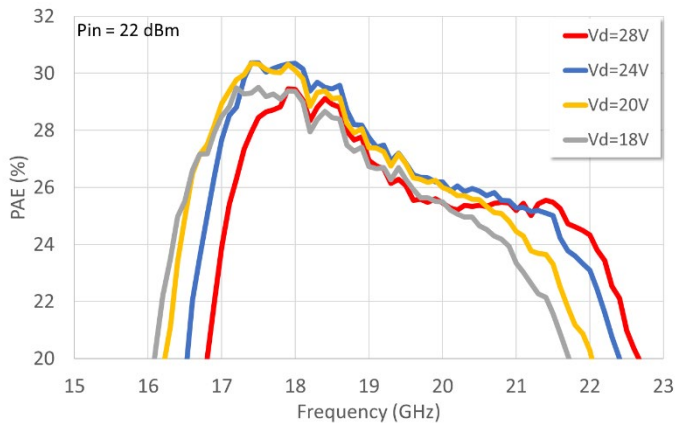
Power Sweep



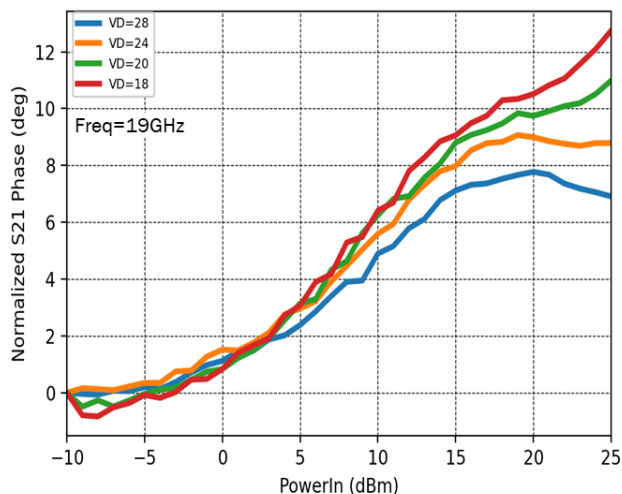
Power vs Supply Voltage



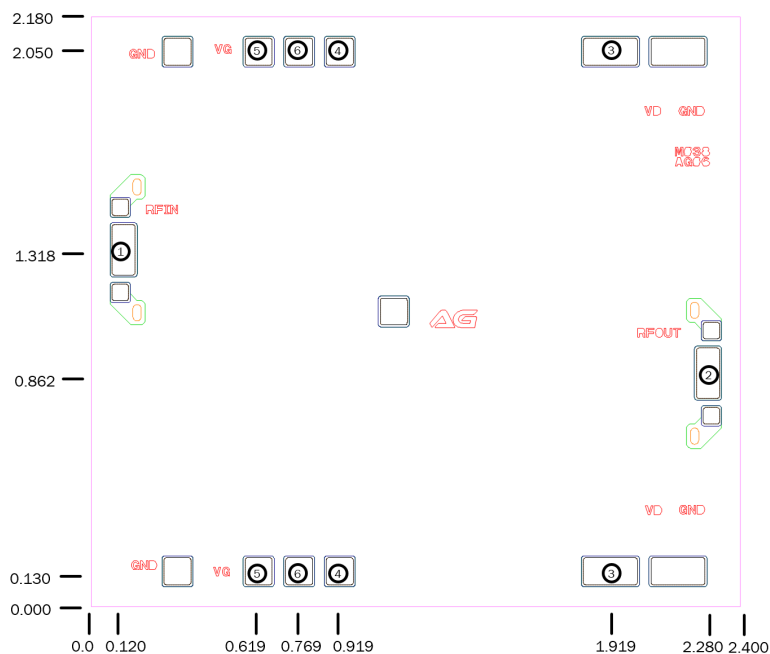
PAE vs Supply Voltage



AM TO PM



Outline Drawing (dimensions in mm)



Pad Descriptions

| Pad | Function | Pad Size | Description |
|------------|----------|-----------------|---|
| 1 | RFIN | 100x200 μ m | AC coupled 50 Ω Matched |
| 2 | RFOUT | 100x200 μ m | AC coupled 50 Ω Matched |
| 3 | VD | 214x114 μ m | Drain Power Supply voltage, bypass capacitors needed* |
| 4 | VD2 | 114x114 μ m | No connect, Alternate Drain Power Supply voltage |
| 5 | VG | 114x114 μ m | Gate Power Supply voltage, bypass capacitors needed* |
| 6 | VG2 | 114x114 μ m | No connect, Alternate Gate Power Supply voltage |
| Die Bottom | GND | Backside | Epoxy/Solder to Baseplate |

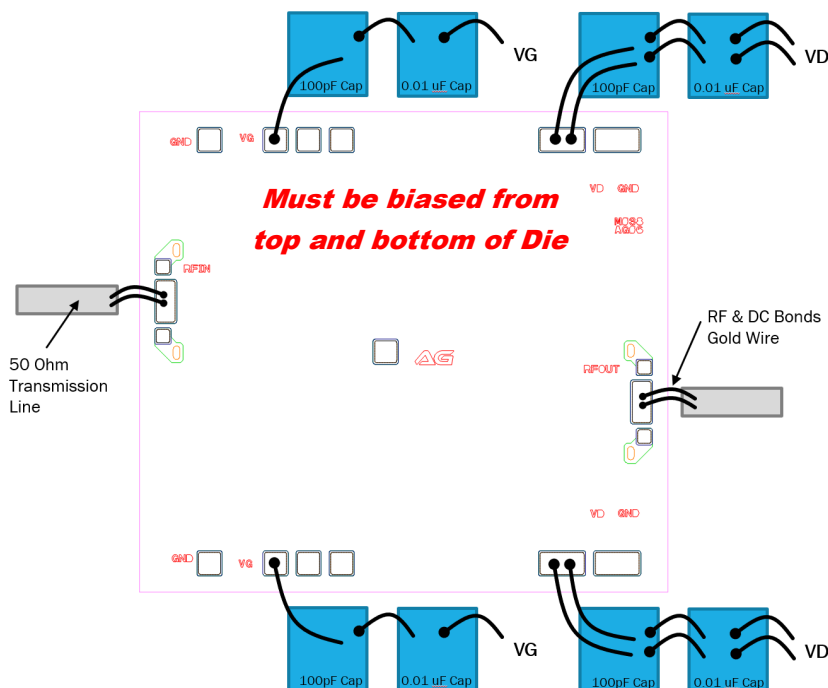
*See Assembly Diagram—Biasing is required on both sides of die

Absolute Maximum Ratings

| | |
|--------------------------|--------------|
| Drain Bias Voltage (VDD) | +28V DC |
| RF Input Power (RFIN) | +36dBm* |
| Channel Temperature | 200°C |
| Storage Temperature | -65 to 150°C |
| Operating Temperature | -55 to 85°C |

*To be tested

Assembly Diagram



Assembly Notes

1. Die Thickness is 100 μ m
2. Backside and Bondpad metallization: 5 μ m gold
3. High thermal conductivity Silver Epoxy or AuSn Eutectic attach MMIC



Die Packaging Information

- GP-4 (Gel-Pak)

Biasing and Operation

The AGM-038 is biased with a positive drain supply and negative gate supply. Performance is optimized when the drain voltage is set to V_{dq} . The preferred biasing procedure is as follows:

Turn ON procedure:

1. Set VG to -3.0V.
2. Set VD to V_{dq} .
3. Adjust VG more positive until $I_d = I_{dq}$.
4. Apply RF signal.

Turn OFF procedure:

1. Turn off RF signal.
2. Reduce VG to -3.0V. I_d should be 0mA.
3. Turn off VD.
4. Turn off VG.

| | | | |
|-------------------------------|---|--|-------------|
| <p>Datasheet vM038.05</p> | <p>Information on this datasheet is believed to be accurate and reliable. Specifications are subject to change without notice</p> | <p>For price, delivery, and to place an order contact: AmpliTech Sales 155 Plant Avenue, Hauppauge, NY 11788 USA Tel. +1 631.521.7831 Order online at www.AmpliTechInc.com</p> | <p>Pg.5</p> |
|-------------------------------|---|--|-------------|